Isolation Voltage	V_{iso}	5000 Ŷ	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	Ņ
Junction Temperature	T_j	125	Ņ
Storage Temperature	T_{stg}	-40 ~ 125	Ņ
Soldering Temperature	T_{sol}	260	Ņ
Peak pulse voltage (Ŧ= 25 Ņ ; non-repetitive,off-state)	V_{pp}	3	kV

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9[9/¢ wL/! [/I! w ! /¢9 (Temperature = 25 ÁC)

Parameter	Symbol	Condition	Min.	Typ.	. . !

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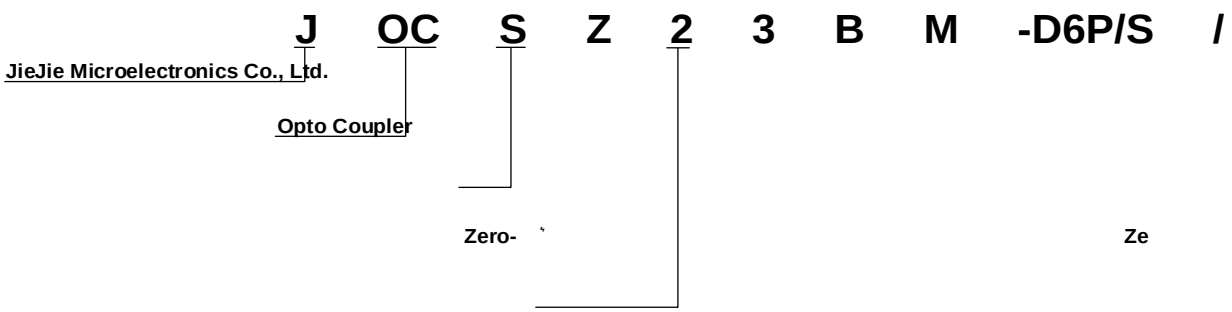

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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

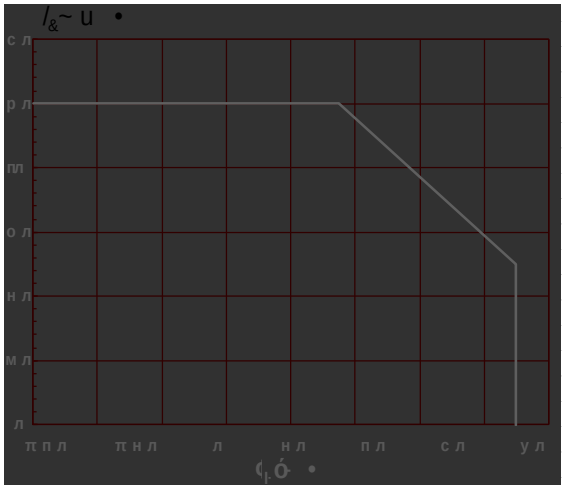

FIG.2: On-state Terminal Current vs. Ambient Temperature

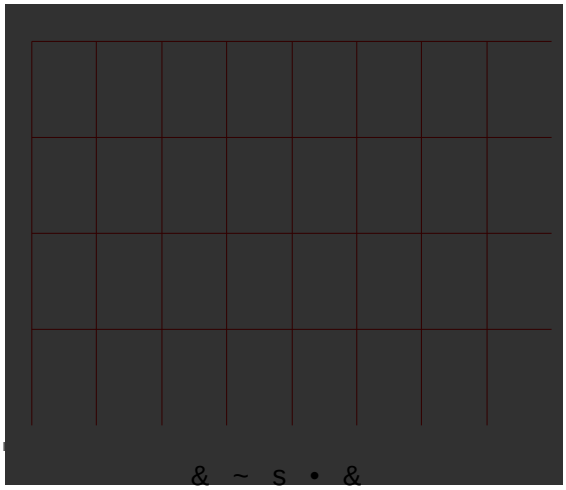

FIG.7: On-state c h aracteristics

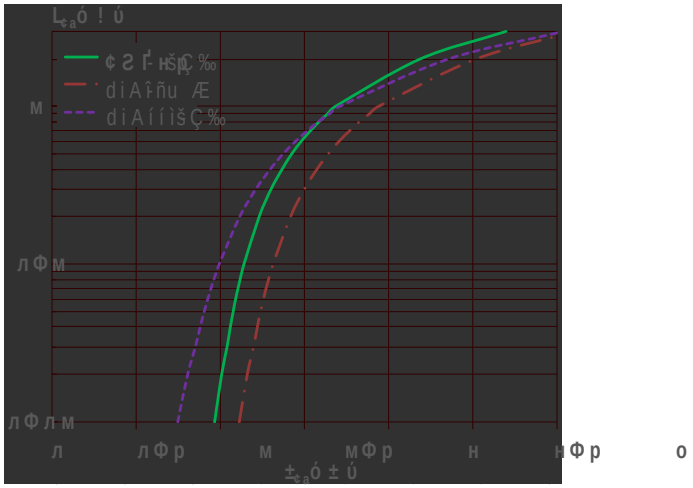

FIG.8: Normali z ed H oldin g Current vs. Ambient Temperature

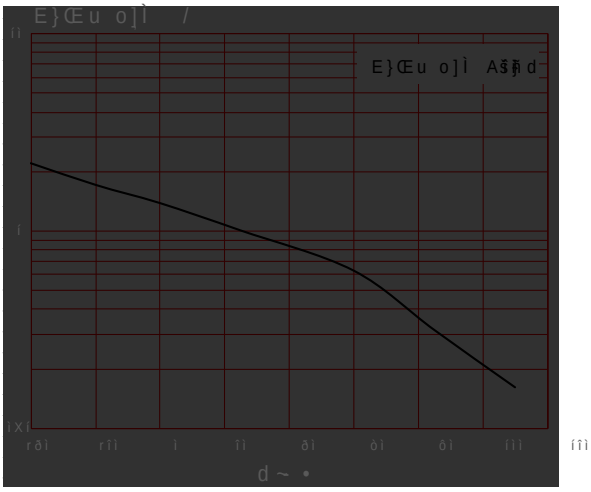

FIG.9: Turn On Time vs. For w ard Current

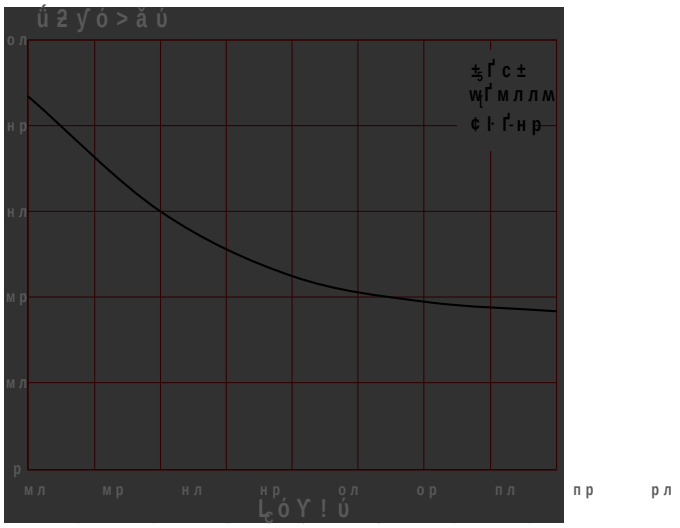

FIG.10: Normali z ed In h ibit Volta g e vs. Ambient Temperature

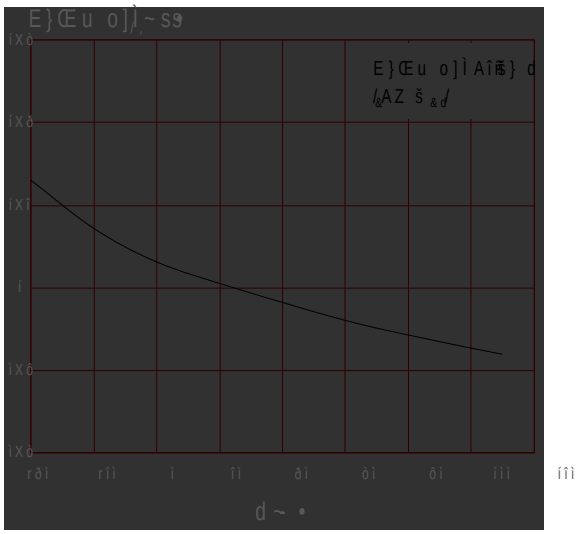

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FIG.11: Test Circuits o f Turn On Time

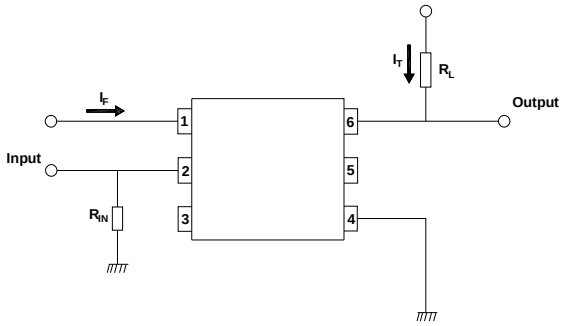


FIG.12: Wave f orms o f Turn On Time

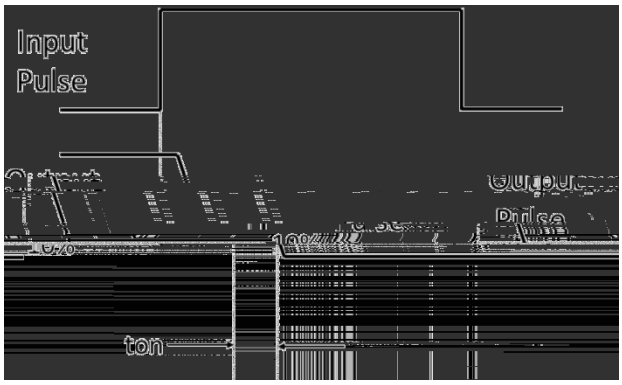
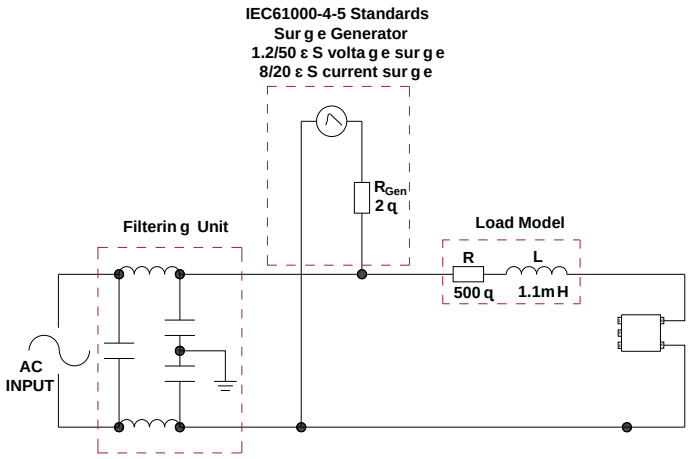


FIG.13: Test circuit f or inductive and resistive loads to IEC-61000-4-5 standards



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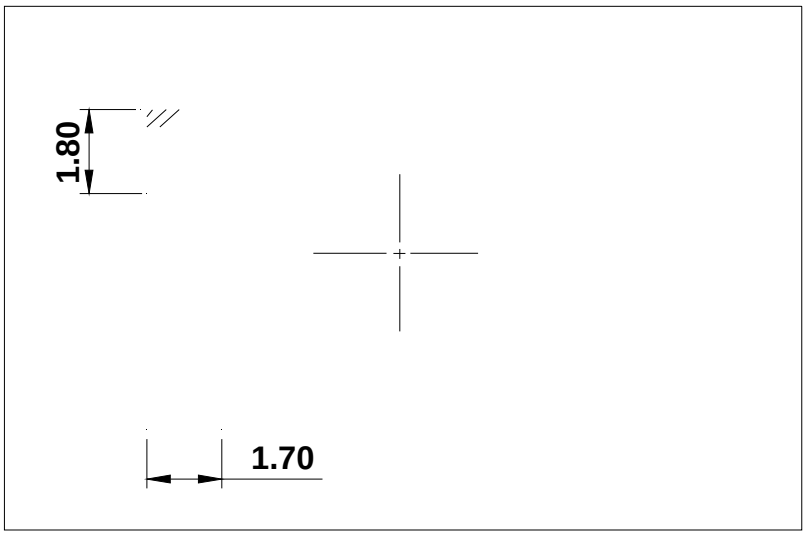
Option SMD



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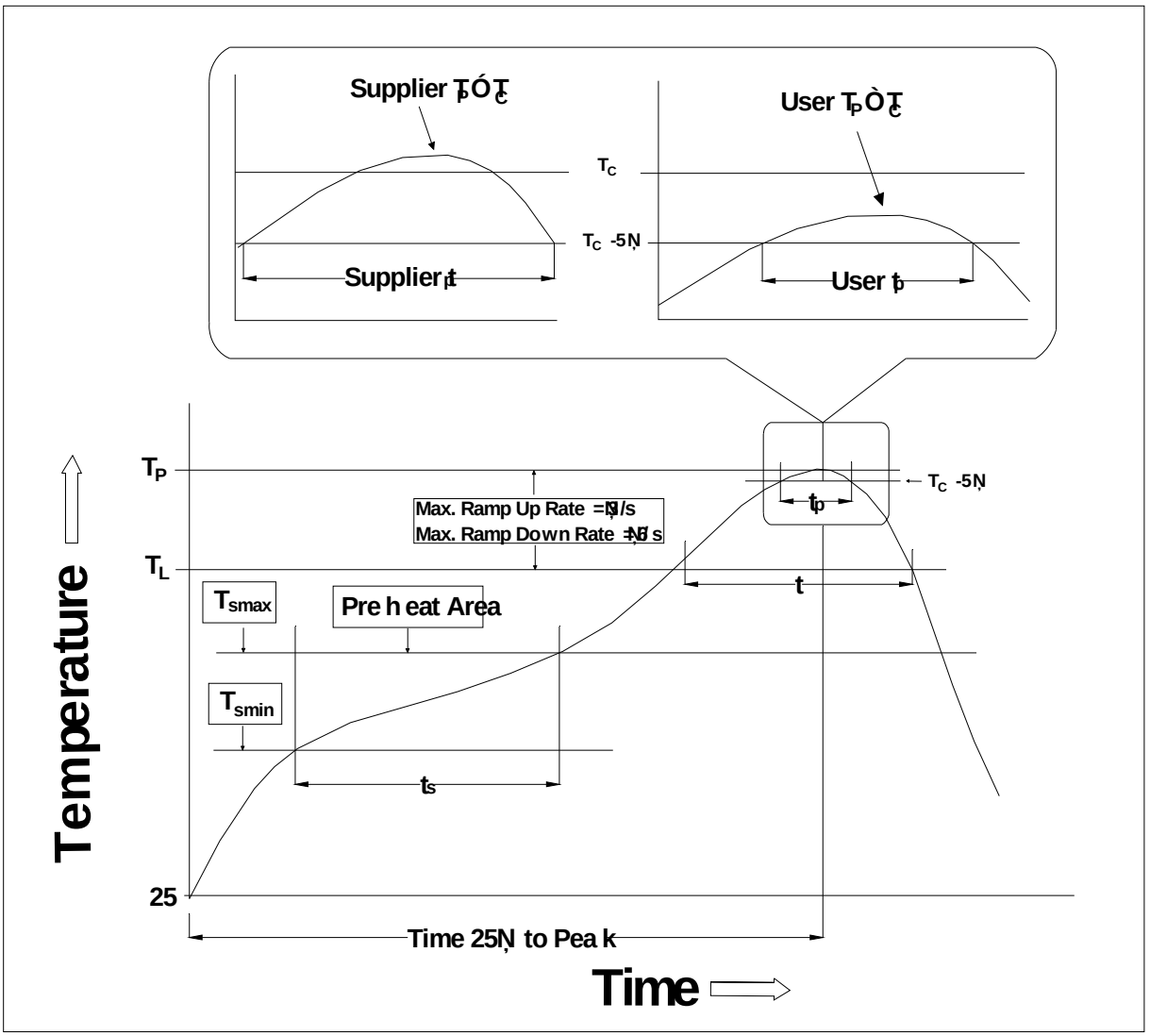

Temperature Min. (Tsmin)	150Ņ
Temperature Max. (Tsmax)	200Ņ
Time (ts) f rom (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3Ņ/second max.
Li q uidus Temperature (TL)	217Ņ
Time (tL) Maintained Above (TL)	60-120 seconds
Pea k Body Pac k a g e Temperature	260Ņ + 0Ņ/-5Ņ
Time (tP) wit hŅ inc5f 260Ņ	10 seconds
Ramp-down Rate (TP to TL)	6Ņ/second max.

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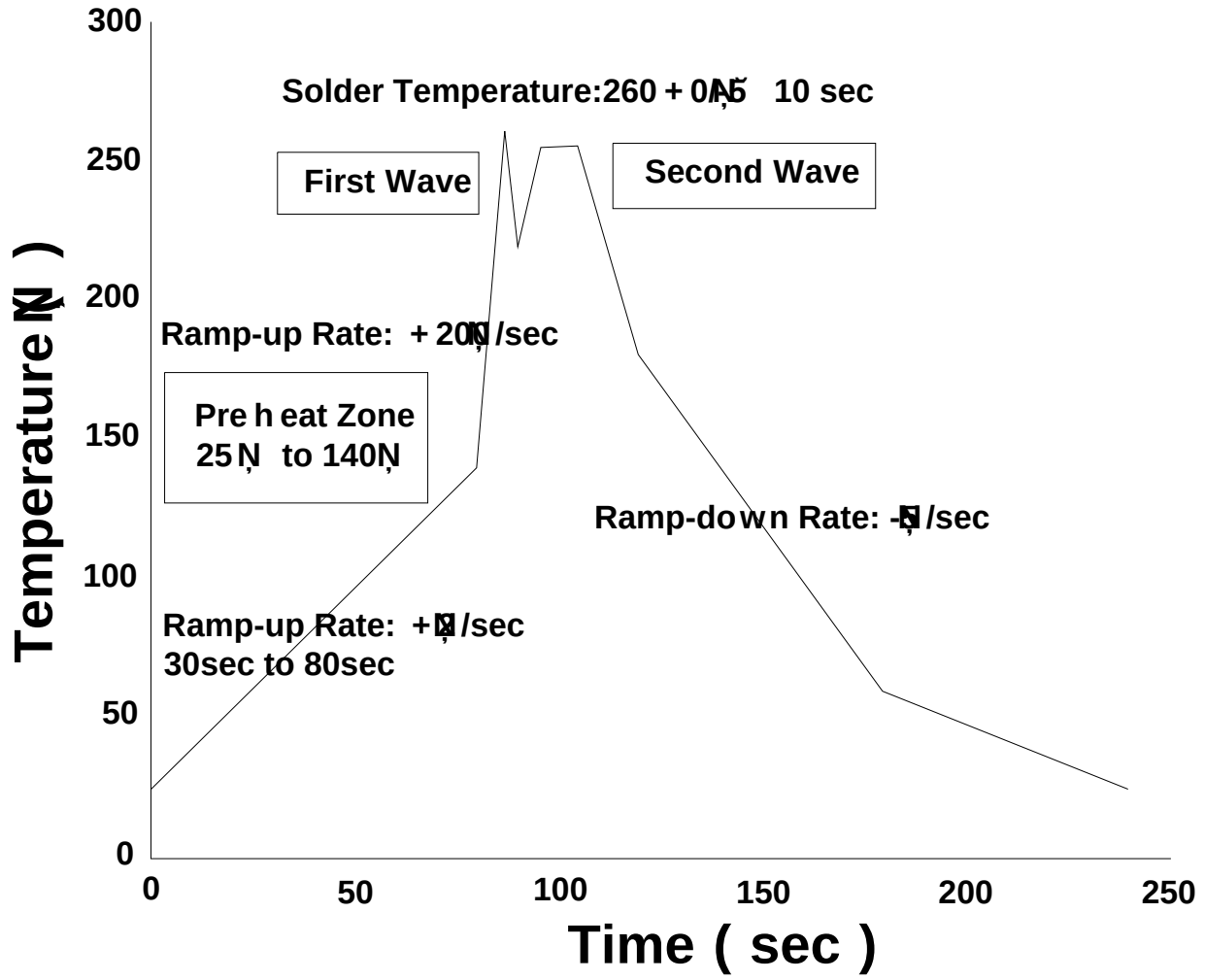

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Solderin g Temperature	360 ¤ 5Ņ
Solderin g Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.

2. Avoid direct contact between the epoxy body